

# SOT1379-4

WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

23 June 2020

Package information

## 1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP6
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	24-06-2019
Manufacturer package code	98ASA01480D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.6425	0.66	0.6775	mm
package width	0.4325	0.45	0.4675	mm
seated height	-	0.28	0.305	mm
nominal pitch	-	0.22	-	mm
actual quantity of termination	-	6	-	



WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

2 Package outline

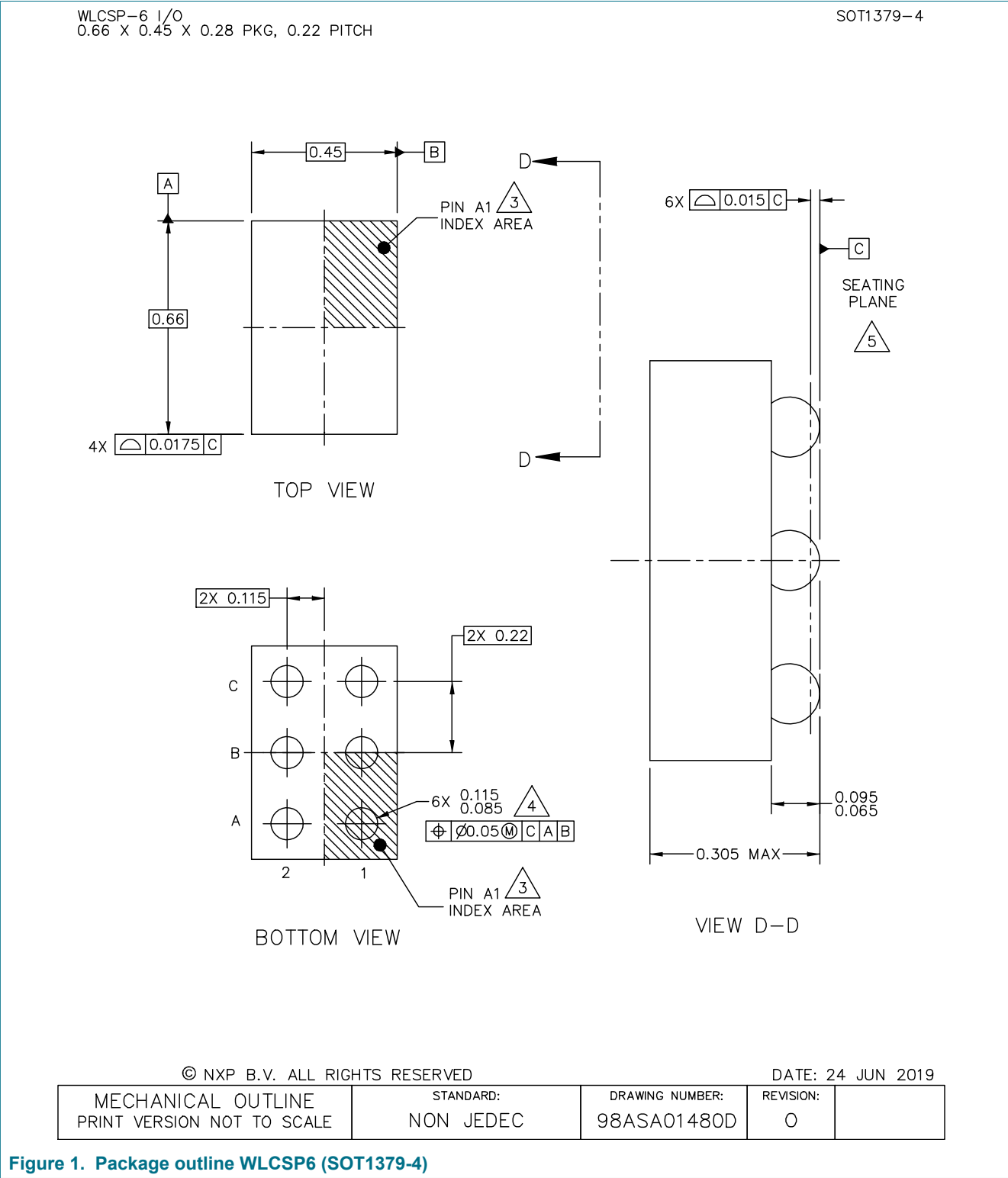
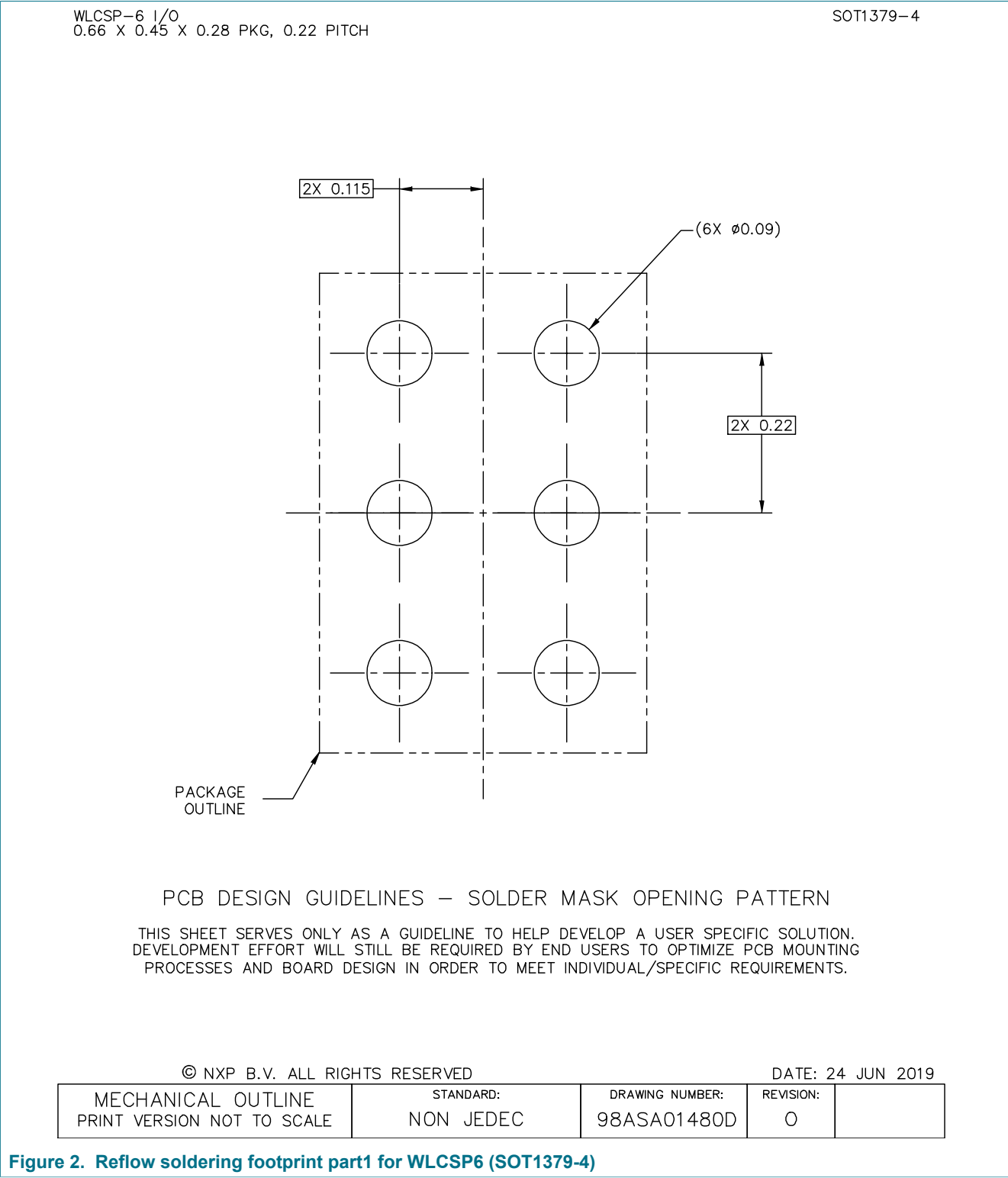


Figure 1. Package outline WLCSP6 (SOT1379-4)

WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

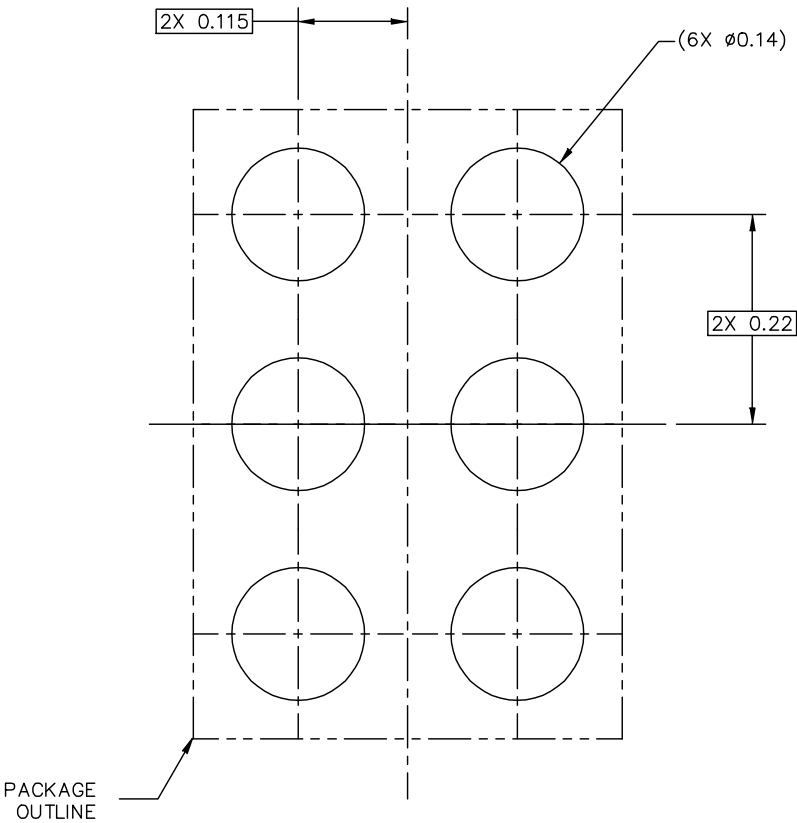
3 Soldering



WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

WLCSP-6 I/O  
0.66 X 0.45 X 0.28 PKG, 0.22 PITCH

SOT1379-4



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 24 JUN 2019

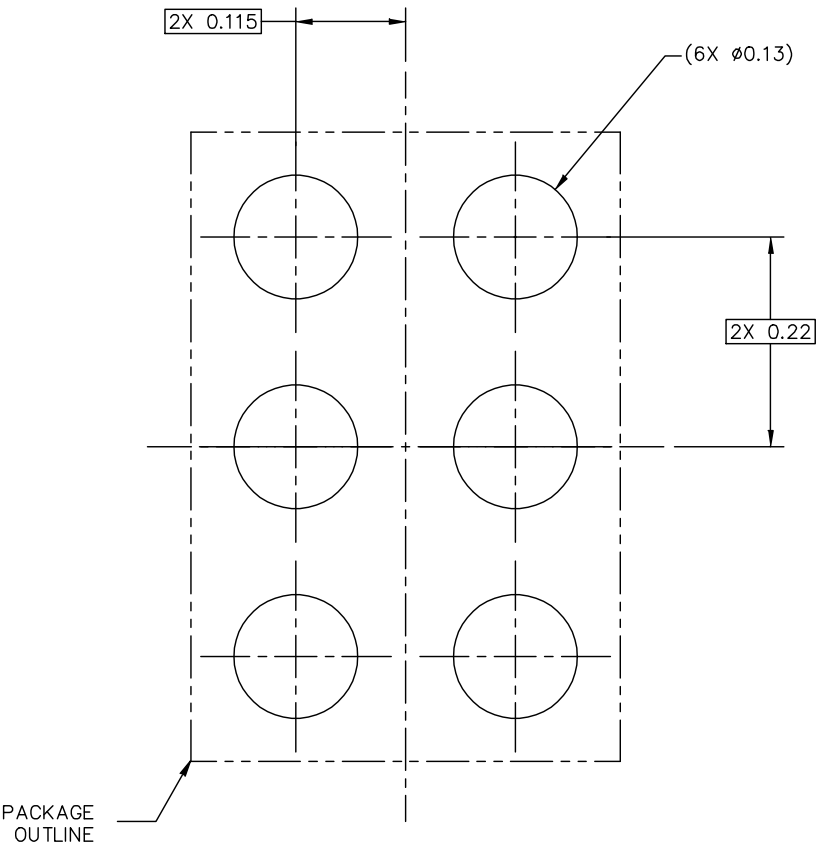
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01480D	REVISION: O	
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Figure 3. Reflow soldering footprint part2 for WLCSP6 (SOT1379-4)

WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

WLCSP-6 I/O  
0.66 X 0.45 X 0.28 PKG, 0.22 PITCH

SOT1379-4



RECOMMENDED STENCIL THICKNESS 0.06

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for WLCSP6 (SOT1379-4)

WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

WLCSP-6 I/O  
0.66 X 0.45 X 0.28 PKG, 0.22 PITCH

SOT1379-4

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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DATE: 24 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01480D	REVISION: 0	
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Figure 5. Package outline note of WLCSP6 (SOT1379-4)

## 4 Legal information

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body

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